

UM11443

NXP Wi-Fi and Bluetooth Debug Feature Configuration Guide for i.MX RT Platforms

Rev. 6 — 14 March 2022

User manual

Document information

Information	Content
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Abstract	Describes the debug configurations to generate various Wi-Fi driver/feature logs and Bluetooth protocol debugging methods.



1 Revision history

Revision history

Rev	Date	Description
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v.6	2022314	Modifications <ul style="list-style-type: none"> • Section 2.3 "References": updated the path to <i>UM11441</i> and <i>UM11442</i> user manuals • Table 3 "Bluetooth debug log configurations": <ul style="list-style-type: none"> – Added <i>CONFIG_BT_DEBUG_SPP</i> macro – Added <i>CONFIG_BT_DEBUG_RFCOMM</i> macro – Removed <i>CONFIG_WMM</i> • Section 4.2.3 "Run the Bluetooth demo application": removed the content on demo start-up logs

2 About this document

2.1 Purpose and scope

This document describes the debug configurations to generate various Wi-Fi driver/feature logs and Bluetooth protocol debugging methods. It details Wi-Fi/Bluetooth sample application using i.MX RT1060 EVK board and NXP-based wireless module for debugging. The purpose of this document is to provide more flexibility to the user for the debug configurations and aims at providing a quick understanding of the debugging techniques.

2.2 Considerations

This document does not include wireless module information, i.MX RT product information, hardware interconnection, board settings, bring-up, IDE setup, SDK download, as these are covered in [UM11441](#) and [UM11442](#).

2.3 References

Table 1. References

Reference type	Description
Web page	NXP - Getting Started with Wi-Fi on i.MX RT platforms (link)
User manual	NXP - UM11441 - Getting Started with NXP-based Wireless Modules and i.MX RT Platform Running RTOS SDK Documents bundle: <i>SDK_<version>_EVK-<RT-Platform>\docs\wireless</i>
User manual	NXP - UM11442 - Wi-Fi and Bluetooth Demo Applications for i.MX RT Platforms User Guide SDK Documents bundle: <i>SDK_<version>_EVK-<RT-Platform>\docs\wireless</i>
Configuration file	NXP – wifi_config.h <i>evk<RT-Platform>wifi_<example>\source\wifi_config.h</i>
Configuration file	NXP – app_config.h <i>evk<RT-Platform>wifi_<example>\source\app_config.h</i>

3 Wi-Fi debug features and configurations

This section shows the list of user-configurable Wi-Fi debug macros available in i.MX RT MCUXpresso SDK and how to get different Wi-Fi debug logs based on the features by enabling/defining these macros at the time of application execution. This section also explains the usage of *wifi_cli_fw_dump* application and firmware dump collection in case of Wi-Fi firmware/firmware host communication failure.

3.1 Wi-Fi debug configurations

To enable the debug logs, use the macros listed in the table below along with the source file name. Some of the debug macros are already defined and others can be defined in the header file.

For example, to define `CONFIG_ENABLE_ERROR_LOGS` macro, add the following line in *wifi_config.h* file.

```
#define CONFIG_ENABLE_ERROR_LOGS 1
```

Table 2. Wi-Fi debug log configurations

Debug macros	Default macro value	File name	Details
CONFIG_ENABLE_ERROR_LOGS	1	<i>wifi_config.h</i>	Enable error logs for Wi-Fi (Includes DHCPD, lwIP, os [port], WLCM, Wi-Fi driver modules)
CONFIG_ENABLE_WARNING_LOGS	1	<i>wifi_config.h</i>	Enable warning logs for Wi-Fi (Includes DHCPD, WLCM, Wi-Fi driver modules)
CONFIG_WLCMGR_DEBUG	Undefined	<i>wifi_config.h</i>	Enable wireless connection manager debug logs
CONFIG_WIFI_EXTRA_DEBUG	Undefined	<i>wifi_config.h</i>	Additional debugging information for the Wi-Fi driver
CONFIG_WIFI_EVENTS_DEBUG	Undefined	<i>wifi_config.h</i>	Dump event codes received from the Wi-Fi firmware
CONFIG_WIFI_CMD_RESP_DEBUG	Undefined	<i>wifi_config.h</i>	Enable host command and response debug logs (no hex dump)
CONFIG_WIFI_SCAN_DEBUG	Undefined	<i>wifi_config.h</i>	Enable scan debug logs
CONFIG_WIFI_IO_INFO_DUMP	Undefined	<i>wifi_config.h</i>	Enable information dump about input/output data packets
CONFIG_WIFI_IO_DEBUG	Undefined	<i>wifi_config.h</i>	Enable IO debug logs
CONFIG_WIFI_IO_DUMP	Undefined	<i>wifi_config.h</i>	Enable SDIO send/receive dump
CONFIG_WIFI_MEM_DEBUG	Undefined	<i>wifi_config.h</i>	Enable Wi-Fi module memory related debug logs like allocation and free
CONFIG_WIFI_AMPDU_DEBUG	Undefined	<i>wifi_config.h</i>	Enable AMPDU debug level logs
CONFIG_WIFI_TIMER_DEBUG	Undefined	<i>wifi_config.h</i>	Enable timer debug level logs
CONFIG_WIFI_SDIO_DEBUG	Undefined	<i>wifi_config.h</i>	Enable SDIO debug level logs
CONFIG_WIFI_FW_DEBUG	Undefined	<i>wifi_config.h</i>	Enable Wi-Fi Firmware debug logs

3.2 Collect Wi-Fi firmware dump logs using *wifi_cli_fw_dump*

This section describes the use of *wifi_cli_fw_dump* application for which support is enabled on i.MX RT1060 EVK board and explains how to get the Wi-Fi firmware dump in case of Wi-Fi firmware/host communication failure.

This application includes similar commands to *wifi_cli* application. For more details on *wifi_cli* application usage and configuration please refer to [UM11442](#).

3.2.1 Software download and i.MX RT image setup

Please refer to [UM11441](#) for the SDK download and image setup steps.

3.2.2 Pre-requisites before running the application

Below are the prerequisite to collect the firmware dump:

- Define `CONFIG_WIFI_FW_DEBUG` macro in the *wifi_config.h* header file
- Rebuild and flash *wifi_cli_fw_dump* application
- Plug the USB stick in the USB OTG (J9) slot which is located beside the Ethernet slot on i.MX RT1060 EVK board. Since J9 is a Micro USB slot, use a USB stick with a Micro USB to USB converter. J9 slot is shown in [Figure 1](#).

Note: Format a USB 2.0 stick as a FatFS disk. Other types like NTFS are not supported.

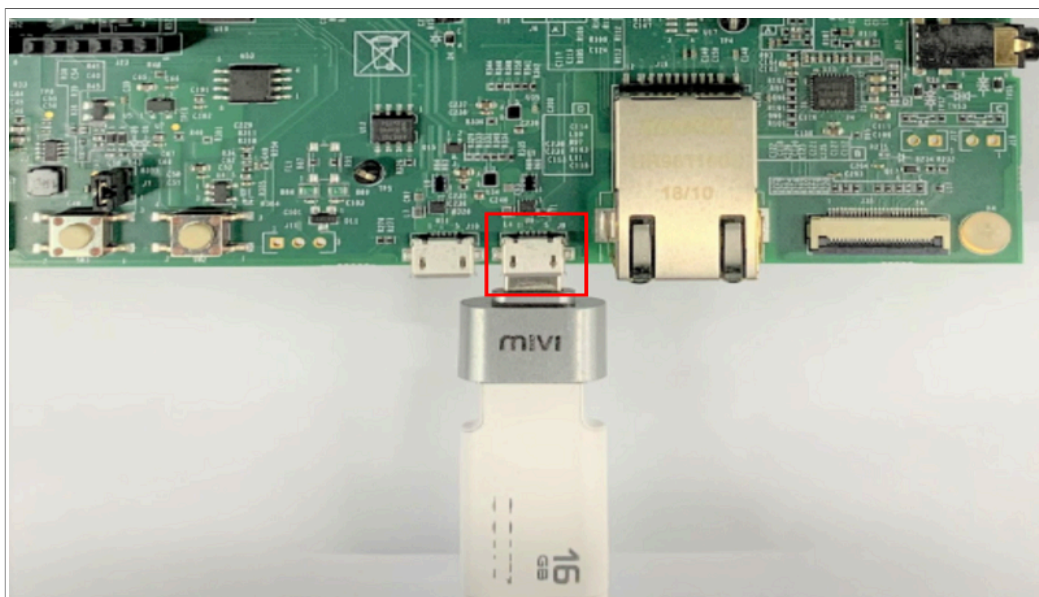


Figure 1. USB stick plugged in i.MXRT1060 EVK board

3.2.3 Run the Wi-Fi demo application

This section describes how to capture the Wi-Fi firmware dump logs and save them on the USB drive plugged into i.MX RT1060 EVK board.

Once the image is flashed on the board, power reset the i.MX RT1060 EVK board and check the console for application start up logs.

Demo start-up logs

The following logs can be observed once the devices—i.MX RT1060 EVK board and NXP-based wireless module—are up and running.

First, the Wireless module firmware is loaded through the SDIO interface. Once the firmware is successfully initialized and loaded, Wi-Fi MAC address is printed on the console as shown below.

```
=====
wifi cli fw dump demo
=====
Initialize CLI
=====
Initialize WLAN Driver
=====
MAC Address: 00:13:43:7F:9C:9F
host init done
[net] Initialized TCP/IP networking stack
=====
app_cb: WLAN: received event 10
=====
app_cb: WLAN initialized
=====
WLAN CLIs are initialized
=====
CLIs Available:
=====
help
wlan-version
wlan-mac
wlan-scan
wlan-scan-opt ssid <ssid> bssid ...
wlan-add <profile_name> ssid <ssid> bssid...
wlan-remove <profile_name>
wlan-list
wlan-connect <profile_name>
wlan-start-network <profile_name>
wlan-stop-network
wlan-disconnect
wlan-stat
wlan-info
wlan-address
wlan-get-uap-channel
wlan-get-uap-sta-list
wlan-ieee-ps <0/1>
wlan-deep-sleep-ps <0/1>
ping [-s <packet_size>] [-c <packet_count>] [-W <timeout in sec>]
  <ip_address>
iperf [-s|-c <host>|-a|-h] [options]
dhcp-stat
=====
```

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Whenever a Wi-Fi firmware or SDIO communication failure occurs, the firmware dump is collected and stored in the USB stick plugged into iMXRT1060 EVK board. This dump is used later to analyze the crashed task call stack.

The reference console log which represents the failure is shown below:

```
# [wifi_io] Error: sdio_drv_write failed (0)
[wifi] SDIO Func0 (0-0x9): 43 03 02 02 03 02 00 02 03 00
[wifi] SDIO Func1 (0x10-0x17): 00 00 00 80 f8 ff ff ff
[wifi] SDIO Func1: (0x8) c3 (0x58) 00 (0x5c) 40 (0x5d) 00 (0x60) 07
(0x61) 0c (0x62) 00 (0x64) 00 (0x65) 00 (0x66) 00 (0x68) 00 (0x69) 00
(0x6a) 00
[wifi] SDIO Func1 (0xe8-0xf2): dc fe f2 00 a9 00 00 00 00 01 70
[wifi] SDIO Func1 (0xe8-0xf2): dc fe f3 00 aa 00 00 00 00 01 70
.....fatfs test.....
fatfs mount as logical drive 1.....success
[wifi] ==== DEBUG MODE OUTPUT START: 187392904.187392904 ====
[wifi] Start DUMP output 188965782, please wait...
[wifi] ==== DEBUG MODE OUTPUT END: 417214601 ====
```

Note: Please wait for some time until the firmware dump write with the file name *FW_DUMP.BIN* is fully transferred to the attached USB stick. On write completion *DEBUG MODE OUTPUT END* print shows on the console.

4 Bluetooth debug features and configurations

This section shows the steps to capture HCI logs for Bluetooth using *a2dp_sink* application. The HCI logs are used to analyze the Bluetooth Host and Controller communication. It also provides the steps to extract the link key for the Bluetooth Classic used to decrypt the Bluetooth sniffer logs.

4.1 Bluetooth Classic/Bluetooth LE debug configurations

To enable the debug logs, use the macros listed in the table below along with the source file name.

For example, to define `CONFIG_BT_SNOOP` macro, add the following line in *app_config.h* file.

```
#define CONFIG_BT_SNOOP 1
```

Table 3. Bluetooth debug log configurations

Debug macros	Default macro value	File name	Details
CONFIG_BT_SNOOP	Undefined	app_config.h	Enable the HCI logs capturing and store data in USB driver.
CONFIG_BT_DEBUG	Undefined	app_config.h	Enable the debug print feature.
CONFIG_BT_DEBUG_HCI_CORE	Undefined	app_config.h	Enable the debug prints for HCI interface.
CONFIG_BT_DEBUG_CONN	Undefined	app_config.h	Enable the debug prints for connection.
CONFIG_BT_DEBUG_GATT	Undefined	app_config.h	Enable the debug prints for GATT module.
CONFIG_BT_DEBUG_ATT	Undefined	app_config.h	Enable the debug prints for ATT module.
CONFIG_BT_DEBUG_L2CAP	Undefined	app_config.h	Enable the debug prints for L2CAP module.
CONFIG_BT_DEBUG_A2DP	Undefined	app_config.h	Enable the debug prints for A2DP module.
CONFIG_BT_DEBUG_HFP_AG	Undefined	app_config.h	Enable the debug prints for HFP Audio gateway.
CONFIG_BT_DEBUG_HFP_HF	Undefined	app_config.h	Enable the debug prints for HFP device.
CONFIG_BT_DEBUG_SPP	Undefined	app_config.h	Enable the debug prints for SPP
CONFIG_BT_DEBUG_RFCOMM	Undefined	app_config.h	Enable the debug prints for RFCOMM

4.2 Capture and analyze HCI logs using *a2dp_sink*

This section describes the use of *a2dp_sink* application for which support is enabled on i.MX RT1060 EVK board with an NXP-based wireless module and it helps to capture Bluetooth HCI logs. For more details on *a2dp_sink* application usage and configuration, refer to [UM11442](#).

4.2.1 Software download and i.MX RT image setup

Refer to [UM11441](#) for the SDK download and image setup steps.

4.2.2 Pre-requisites before running the application

- **Define** `CONFIG_BT_SNOOP` macro in *app_config.h* file. See [Section 4.1](#).
- **Rebuild** and **flash** *a2dp_sink* application
- **Connect** the USB Drive
Plug the USB Drive into the i.MX RT1060 EVK board. See [Section 3.2.2](#).
- **Setup Wireshark tool**
The Wireshark tool is required to open and analyze the HCI logs. Download and install *Wireshark* tool for Windows and Mac OS from [here](#).
Steps to install *Wireshark* tool on a computer running Linux Ubuntu:

```
sudo add-apt-repository ppa:wireshark-dev/stable
sudo apt update
sudo apt install wireshark
```

4.2.3 Run the Bluetooth demo application

This section describes how to capture the Bluetooth HCI logs saved in the USB drive plugged into i.MX RT1060 EVK board.

Once the image is flashed on the board, power reset the i.MX RT1060 EVK board.

The demo application first loads the Wi-Fi and Bluetooth module firmware through the SDIO interface.

Next, the application automatically turns on the discoverable and connectable mode for Bluetooth Classic.

The following logs can be observed once the i.MX RT EVK board and NXP-based wireless module are up and running.

```
Bluetooth initialized
BR/EDR set connectable and discoverable done
```

Pair a phone with *a2dp_sink*

At this point, the stack is ready to accept incoming connections from any peer device. Take the mobile phone and use the **Pair new device** option in Bluetooth settings to scan, connect and pair with the i.MX RT1060 EVK and NXP-based wireless module named as *a2dp_sink*.

The following log shows on the console upon the successful Bluetooth connection.

```
Connected
Security changed: 7A:5A:2B:2E:9E:C3 (0xad) level 2
a2dp connected success
```

Disconnect *a2dp_sink* from the phone

The following log shows on the console.

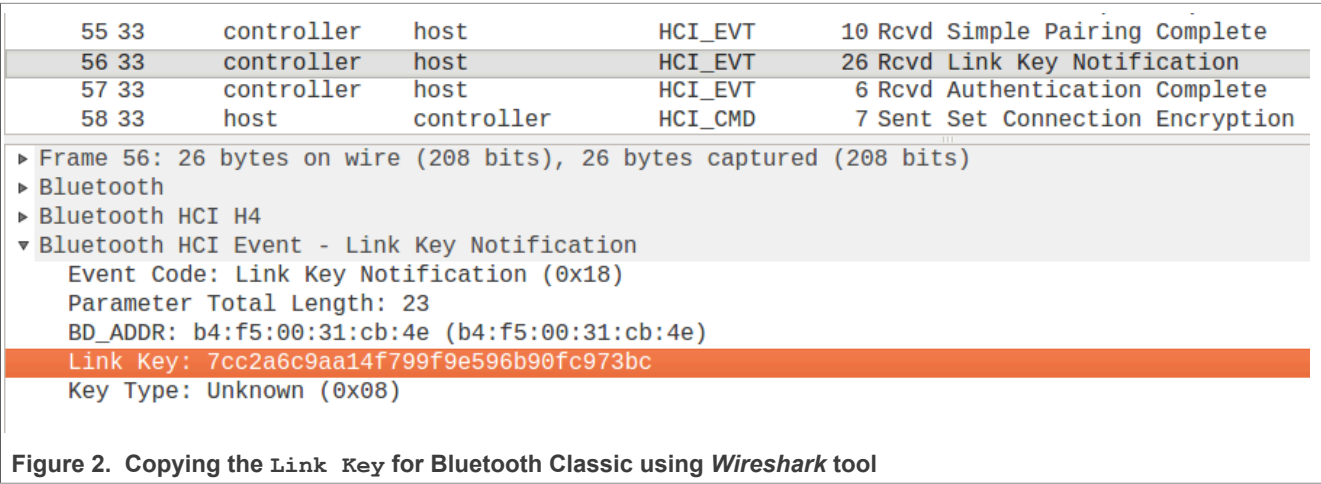
```
Disconnected (reason 0x13)
```

Unplug the USB drive and connect it to the laptop

The file named “*btsnoop*” is available in the USB drive. The *Wireshark* tool can be used to open the file and analyze the logs.

Extract the Link Key for Bluetooth Classic

Open the captured HCI Logs in *Wireshark* tool and search for Link Key Notification event. Copy the Link Key to use for the sniffer logs decryption.



5 Acronyms and abbreviations

Table 4. Acronyms and abbreviations

Acronym	Definition
A2DP	Advanced audio distribution profile
AMPDU	Aggregate – MAC protocol data unit
AMSDU	Aggregate – MAC service data unit
AP	Access point
APPL	Application
DHCP	Dynamic host configuration protocol
EVK	Evaluation kit
FW	Firmware
HCI	Host controller interface
IDE	Integrated development environment
IE	Information element
IP	Internet protocol
lwIP	Lightweight IP
OTG	On the go
SD	Secure digital
SDK	Software development kit
STA	Station/client
SW	Software
USB	Universal serial bus
WLAN	Wireless local area network
WLCM	Wireless connection manager
WMM	Wi-Fi multimedia

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